



Material Composition Sheet

Product: GS1510-CQR
 Package Type: DQFP-128 pin (66/tray)
 Manufacturer: Gennum Corporation

Date: 16-Jan-2007

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		29.91	Al	0.18	0.60	6018
			Si	29.73	99.39	993982
			Sub-total:	29.91	99.99	1000000
Die Attach	8360	3.80	Ag	2.85	75.00	750000
			Curing agent & hardener	0.19	5.00	50000
			Epoxy Resin	0.76	20.00	200000
			Sub-total:	3.80	100.00	1000000
Lead Finish External		31.51	Pb	4.73	15.01	150111
			Sn	26.78	84.98	849889
			Sub-total:	31.51	99.99	1000000
Lead Finish Internal		1.15	Ag	1.15	100.00	1000000
			Sub-total:	1.15	100.00	1000000
Leadframe	OLIN 7025	270.80	Cu	260.51	96.20	962001
			Mg	0.41	0.15	1514
			Ni	8.12	2.99	29985
			Si	1.76	0.64	6499
			Sub-total:	270.80	99.98	999999
Marking Ink	Teca 261	0.10		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME 6600CS	1269.73	Antimony Trioxide	25.39	1.99	19996
			Bromine	7.62	0.60	6001
			Epoxy Resin	126.97	9.99	99998
			Phenol Resin	81.26	6.39	63998
			Silica Fused	1028.49	81.00	810007
Sub-total:	1269.73	99.97	1000000			
Wires	MGM 7	2.40	Au	2.40	100.00	1000000
			Sub-total:	2.40	100.00	1000000
Total:		1609.40				

GENNUM CORPORATION

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